



Zhu
D.A.C.

CERTIFICATE OF MAILING UNDER 37 CFR 1.8

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on July 26, 2005.


Sue Bromaghim

July 26, 2005

CUSTOMER NO. 36257

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Wayne G. Renken

Title: Process Condition Sensing Wafer and Data Analysis System

Application No.: 10/685,550 Filing Date: October 14, 2003

Examiner: Charles D. Garber Group Art Unit: 2856

Docket No.: SENS.005US1 Conf. No.: 4924

MailStop Petition
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

**PETITION UNDER 37 CFR 1.181
TO WITHDRAW A HOLDING OF ABANDONMENT
AND ALTERNATIVE PETITION UNDER 37 CFR 1.137(b)
TO REVIVE APPLICATION AS UNINTENTIONALLY ABANDONED**

Sir:

Withdrawal of the holding of abandonment in this case is hereby again requested.

A Notice of Abandonment dated February 7, 2005, for failure to respond to the Office Action dated June 29, 2004, was issued in this case. Because an amendment responding to the Office Action was filed on September 27, 2004, the holding of abandonment is submitted to be in error, and it is requested that the holding of abandonment be withdrawn.

A request to withdraw the holding of abandonment was first made on February 16, 2005, nine days after the mail date of the Notice of Abandonment.

Attorney Docket No.: SENS.005US1

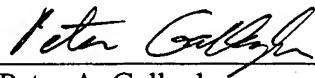
Application No.: 10/685,550

A copy of the Response to the Notice of Abandonment, requesting withdrawal of the holding of abandonment with a copy of the amendment filed on September 27, 2004, and return receipt postcard, is enclosed herewith.

Alternatively, if the holding of abandonment is not withdrawn on the grounds stated above, it is requested that the case be revived under 37 CFR 1.137(b) as unintentionally abandoned. The enclosed copy of the amendment dated September 23, 2004 is submitted to reply to the outstanding Office Action. Any delay beyond the due date in the filing of this amendment was unintentional.

Please charge any fee attendant with this matter to Deposit Account No. 50-2664. This Petition is provided in duplicate.

Respectfully submitted,


Peter A. Gallagher
Reg. No. 47,584

7/26/05
Date

JUL 28 2005



TO:

Fax Sender at 4156930196

Fax Information

Date Received:

Total Pages:

2/16/2005 2:30:24 PM [Eastern Standard Time]

17 (including cover page)

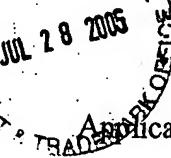
COPY

ADVISORY: This is an automatically generated return receipt confirmation of the facsimile transmission received by the Office. Please check to make sure that the number of pages listed as received in Total Pages above matches what was intended to be sent. Applicants are advised to retain this receipt in the unlikely event that proof of this facsimile transmission is necessary. Applicants are also advised to use the certificate of facsimile transmission procedures set forth in 37 CFR 1.8(a) and (b), 37 CFR 1.6(f). Trademark Applicants, also see the Trademark Manual of Examining Procedure (TMEP) section 306 et seq.

Received
Cover
Page

=====>

16-Feb-2005	11:32am	From-PARSONS HSUE & DE RUYNTZ LLP	4156930196	T-762	P-001	F-614
PARSONS HSUE & DE RUYNTZ, LLP						
655 Montgomery Street, Suite 1800 San Francisco, Ca 94111						
tel 415.318.1160 fax 415.693.0194						
Date	February 16, 2005					
To	United States Patent and Trademark Office Examiner Charles D. Garber					
Fax number	(703) 872-9306					
Tel number	(415) 272-2194					
From	Peter A. Gallagher, Reg. No. 47,584					
Total pages	17					
Subject	Response to Notice of Abandonment dated February 7, 2005					
Your Ref.	Application No. 10/685,550					
Our Ref.	SENS.0005US1					
COMMISSIONER FOR PATENTS P.O. BOX 1450 ALEXANDRIA, VA 22313-1450						
Applicant:	Wayne G. Renken					
Title:	Process Condition Sensing Water and Data Analysis Systems					
Patent No.:						
Issue Date:						
Application No.:	10/685,550					
Filing Date:	October 14, 2003					
Conf. No.:	4924					
Atty Docket No.:	SENS.0005US1					
ENCLOSED.						
1. This Fax Cover Sheet (1 page) 2. Response to Notice of Abandonment (2 pages) 3. Copy of Amendment Transmittal dated September 23, 2004 (1 page) 4. Copy of Amendment in response to June 29, 2004 Office Action dated September 23, 2004 (12 pages) 5. Copy of Return Receipt Postcard with a mailing date of September 23, 2004, date stamped by the Patent and Trademark Office September 27, 2004 (1 page)						
PAQ/baj						
<small>THIS FAXIMILE IS SENT BY A LAW FIRM AND MAY CONTAIN INFORMATION THAT IS CONFIDENTIAL OR ATTORNEY-CLIENT IF YOU ARE NOT THE INTENDED RECIPIENT, PLEASE NOTIFY US IMMEDIATELY AND RETURN THIS MESSAGE AND ANY ATTACHMENT TO US BY MAIL.</small>						
PAGE 1/17 RCVD AT 2/16/2005 2:30:24 PM [Eastern Standard Time] 8V9/USPTO-EFAXF-10 DNS:8729308 CSID:4156930196 DURATION (min:sec):04:40						



Applicant(s): Wayne G. Renken

Title: Process Condition Sensing Wafer and Data Analysis System

Application No.: 10/056,906 Filing Date: January 24, 2002

Examiner: Charles D. Garber Group Art Unit: 2856

Docket No.: SENS.005US0 Conf. No.: 2359

Mail Stop Amendment
Commissioner For Patents
P.O. Box 1450
Alexandria, VA 22313-1450

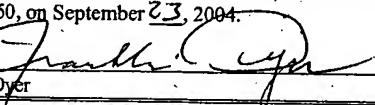
Dear Sir:

Transmitted herewith are the following documents in the above-identified application:

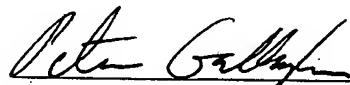
- (1) Amendment (12 pages); and
- (2) Return Postcard.

Certificate of Mailing Under 37 CFR 1.8

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope address to:
Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on September 23, 2004.


Franklin Dyer

Respectfully submitted,

Peter A. Gallagher
Reg. No.47,5849/23/04
Date

JUL 28 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Wayne G. Renken
Title: Process Condition Sensing Wafer And Data Analysis System
Application No.: 10/685,550 Filing Date: October 14, 2003
Examiner: Charles D. Garber Group Art Unit: 2856
Docket No.: SENS.005US1 Conf. No.: 4924

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Sir:

This is in response to the non-final Office Action dated June 29, 2004, setting a period for response expiring on September 29, 2004.

Claim Amendments are reflected in the listing of claims, which begins on page 2 of this paper.

Drawing Amendments are not being made.

Specification Amendments are not being made.

Remarks begin on page 7 of this paper.

CLAIM AMENDMENTS

Please amend claims 21, 36 and 45, cancel claim 26 and add claims 46-54.

Claims 1-20. (Cancelled)

21. (Currently amended) A process condition monitoring device comprising: a substrate having a first perimeter, the substrate comprising sensors to measure the processing conditions of the substrate at different areas of the substrate; and an electronics module having a second perimeter that encloses the same or less area than the first perimeter, the module comprising:

signal acquisition circuitry coupled to an output of the sensors;
data transmission circuitry coupled to the signal acquisition circuitry;
a power source; and

leads connecting the substrate to the electronics module for transmitting signals between the substrate and the electronics module, the leads providing a flexible connection that allows relative movement between the substrate and the electronics module; and

a remote data processing system, and wherein the data transmission circuitry comprises a wireless transceiver to transmit the processing conditions to the remote system.

22. (Original) The monitoring device of claim 21 wherein the signal acquisition circuitry is configured to amplify an output signal of the sensors.

23. (Currently amended) The monitoring device of claim 21 wherein the data transmission circuitry electronics module comprises a micro-controller and is configured to process correct the output signal using sensor calibration coefficients.

24. (Original) The monitoring device of claim 22 wherein the signal acquisition circuitry is further configured to provide an input signal to the sensors.

25. (Original) The monitoring device of claim 24 wherein the input signal comprises input power.

26. (Canceled)

27. (Original) The monitoring device of claim 22 wherein the data transmission circuitry comprises an analog to digital converter.

28. (Original) The monitoring device of claim 21 wherein the data transmission circuitry comprises memory, and wherein the data transmission circuitry stores processing conditions in the memory.

29. (Currently amended) The monitoring device of claim 2126 wherein the remote system is configured to process adjust the output signal using calibration coefficients to provide a final output value.

30. (Original) The monitoring device of claim 21 wherein the transceiver transmits and receives RF signals.

31. (Original) The monitoring device of claim 21 wherein the transceiver transmits and receives IR signals.

32. (Original) The monitoring device of claim 21 wherein the transceiver transmits and receives sonic signals.

33. (Original) The monitoring device of claim 21 wherein the data transmission circuitry comprises one or more connectors to couple a remote system to the device with a communications cable.

34. (Original) The monitoring device of claim 26 wherein the remote system is a microprocessor controlled device.

35. (Original) The monitoring device of claim 21 wherein the processing conditions measured by the sensors comprise one or more of the following conditions: temperature, pressure, flow rate, vibration, ion current density, ion current energy, and light energy density.

36. (Currently amended) The monitoring device of claim 21 wherein the flexible cable is leads form a ribbon cable.

37-44. (Cancelled)

45. (Currently amended) The process condition monitoring device of claim 21 wherein in a first position the electronics module is above or below the substrate, and in a second position the electronics module and the substrate are displaced from each other such that the first and second perimeter do not intersect.

46. (New) The process condition monitoring device of claim 45 wherein, in the first position both the electronics module and the substrate are held by one or more robot hands and in the second position the substrate is within a chamber and the electronics module is outside the chamber.

47. (New) A process condition sensing wafer and data analysis system, comprising:

- an instrumented substrate having sensors that output sensor signal data;
- a data processing system that processes the sensor signal data that is output by the sensors;

- an electronics module that moves independently of the data processing system, the electronics module receiving the sensor signal data from the instrumented substrate, the electronics module subsequently passing the sensor signal data to the data processing system; and

- a physically continuous flexible connection between the electronics module and the instrumented substrate, the connection allowing relative movement of the electronics module with respect to the instrumented substrate.

48. (New) The process condition sensing wafer and data analysis system of claim 47 wherein the electronics module has a memory unit and the sensor signal data are stored in the memory unit prior to the electronics module passing the sensor signal data to the data processing system.

49. (New) The process condition sensing wafer and data analysis system of claim 47 wherein the sensor signal data pass from the electronics module to the data processing module over a wireless connection.

50. (New) The process condition sensing wafer and data analysis system of claim 47 wherein the instrumented substrate has a physical dimension that is equal to the physical dimension of a semiconductor wafer, printed circuit board or flat panel display substrate and the electronics module has a physical dimension that is equal to or less than the physical dimension of the instrumented substrate.

51. (New) The process condition sensing wafer and data analysis system of claim 47 wherein the instrumented substrate is placed in a process environment and the electronics module is placed outside the process environment.

52. (New) A method of sensing and analyzing process conditions in a process environment, comprising:

generating sensor signal data using one or more sensors attached to a substrate within the process environment;

sending the sensor signal data from the sensors to an electronics module that is attached to the substrate by a flexible cable that allows the electronics module to be displaced from the substrate; and

sending the sensor signal data from the electronics module to a data processing system, the electronics module moving separately from the data processing system.

53. (New) The method of claim 52 wherein sensor signal data is generated by the one or more sensors that are in the process environment while the electronics module and the data processing system are not in the process environment.

54. (New) The method of claim 53 wherein sensor signal data is generated by the one or more sensors while the electronics module transmits the sensor signal data to

the data processing system, the data processing system displaced from the electronics module.

REMARKS

Claim Objections

Claims 30-32 were objected to because the claims recite "the transceiver" that was indicated as lacking antecedent basis. Claim 21, from which claims 30-32 depend is amended to provide antecedent basis for this term. Therefore, it is submitted that the objection is overcome.

Claim Rejections

Claim 21 was rejected under 35 USC 102(e) as being anticipated by Akram (US Pat. No. 6,472,242). Claim 21 is amended to include the limitations of claim 26 (now canceled) and additional limitations. Claim 26 was rejected under 35 USC 103(a) as being unpatentable over Akram in view of Lauf (US Pat. No. 5,969,639). The Office Action conceded that Akram "does not teach a remote data processing system and wherein the data transmission circuitry comprises a wireless transceiver to transmit the processing conditions to the remote system." Lauf was cited for this element. It is submitted that no adequate motivation has been provided to combine the teachings of Akram and Lauf and therefore a *prima facie* case of obviousness has not been made. In addition, it is submitted that Lauf teaches away from the claimed combination. Also, additional limitations are added to those previously recited in claim 26 providing additional distinction over the prior art.

Akram teaches "External circuitry 12 includes communication devices in other embodiments of the invention to transmit process conditions," column 3, lines 53-55. The Office Action proposed the combination of "transmitter 750 and antenna 770" of Lauf with the teachings of Akram "in order to eliminate hard wire connection outside the process environment which interferes with probe placement or rotating environment." However, it is not understood how the RF device of Lauf would aid "probe placement" allow "rotating environment" if added to the apparatus of Akram. It is not clear if the Office Action considers external circuitry 12 of Akram to be inside or extend outside a "process environment." If external circuitry 12 of Akram is considered to extend "outside the process environment" then there is still a hard wire connection (connections 14) from the process environment (workpiece 10) to "outside the process environment" even

where the RF transmitter of Lauf is added to resistance thermometer 16. It is not clear how replacing a hard wire connection that is "outside the process environment" would affect probe placement or have other benefits.

The resistance thermometer 16 of Akram is not disclosed as being inside a "process environment" or "rotating environment." Connections 14 may terminate at a resistance thermometer 16 or digital computer (see column 3, lines 47-53) which do not appear to have any protection or structure that would suggest they are located in a process environment. Thus, replacing wired connections from resistance thermometer 16 to some other external unit by an RF connection would not appear to affect "probe placement" or allow "rotating environment."

Replacing external circuitry 12 of Akram with an RF transmitter and antenna would not appear to provide "leads connecting the substrate to the electronics module for transmitting signals between the substrate and the electronics module, the leads providing a flexible connection that allows relative movement between the substrate and the electronics module" of claim 21. Thus, it is submitted that the no motivation has been provided to combine the references to obtain the claimed combination.

Lauf appears to teach away from an apparatus with the structure of claim 21. In particular, Lauf teaches the advantages of a wireless connection from a substrate, "the wires interfere with the placement of probes," column 1, lines 45-46. "Hard-wired wafer cannot be used to measure temperatures in a rotating environment," column 1, lines 48-49. In contrast, claim 21 recites "leads connecting the substrate to the electronics module." Thus, Lauf appears to teach away from the claimed combination of elements. Therefore, it is submitted that no *prima facie* case of obviousness has been made (see MPEP 2143.01 Suggestion or motivation to modify the references: "The prior art must suggest the desirability of the claimed invention").

In short, claim 21 as amended includes three components "a substrate," "an electronics module" and "a remote data processing system." In addition, claim 21 recites "leads connecting the substrate to the electronics module" and "the data transmission circuitry [of the electronics module] comprises a wireless transceiver to transmit to the remote system." Thus, claim 21 is limited to a system having these three components and the specific connections between them. Akram has a workpiece 10 and resistance

thermometer 16 connected by connections 14. Lauf has a wafer 10 and an external receiver linked by RF communication. However, neither reference appears to teach or suggest a three-component system having leads from a substrate to an electronics module and RF communication from the electronics module to a data processing system. Lauf appears to teach away from such a system because Lauf identifies problems with a hard-wired wafer.

In addition, claim 21 as amended includes the limitations "a substrate having a first perimeter" and "an electronics module having a second perimeter that encloses the same or less area than the first perimeter." The "external circuitry 12" of Akram does not appear to be disclosed as having a particular extent with respect to the substrate and therefore appears not to disclose this limitation. Claim 21 as amended also recites "the leads providing a flexible connection that allows relative movement between the substrate and the electronics module." This limitation further distinguishes over apparatus having components with fixed relative positions. Therefore, it is submitted that claim 21 is additionally allowable over the cited prior art.

Claims 22-36 and 45 depend from claim 21 and are therefore submitted to be allowable at least for depending from an allowable base claim. In addition, these claims include additional claim features that are not taught or suggested by the prior art. Claim 23 is amended to clarify the claim language. Claim 29 is amended to depend from claim 21 and to clarify the function of the remote system.

Claims 29 and 34 recite limitations regarding "the remote system." Claims 29 and 34 were rejected under 35 USC 103(a) as unpatentable over Akram as modified by Lauf and further in view of Schwartz. Claim 29 as amended includes, "the remote system is configured to process the output signal using calibration coefficients to provide a final output value. Claim 34 includes, "the remote system is a microprocessor controlled device." These limitations do not appear to be taught or suggested by the cited combination.

Schwartz does not appear to teach or suggest a particular location for adjustment operations such as that of claim 29. Therefore, claim 29, which is limited to the remote system, is submitted to be allowable over this combination. In rejecting claim 34, the Office Action referred to the rejection of claim 23 stating "Schwartz advantageously

taught the system with microprocessor control.” However, such control is not taught as occurring in a remote system such as that of claim 34. Therefore, merely using a microprocessor at some other location does not teach this element. Because this element is not shown by the cited combination of references, claim 34 is submitted to be additionally allowable.

Claim 30 was rejected as unpatentable over Akram in view of Larson (US Pat. No. 6,651,488). The Office Action acknowledged “Akram does not expressly teach a transceiver transmits and receives RF signals.” “Transceiver system 28” of Larson was cited for this claim element. However, Larson describes “wireless interrogation system 28,” column 4, lines 41-42, that appears to have no wires or leads connecting to substrate 14. In contrast, claim 21 from which claim 30 depends recites “leads connecting the substrate to the electronics module.” Thus, Larson does not appear to suggest the structure of claim 30 but rather, Larson (like Lauf) appears to teach away from the claimed structure that has both wires and wireless communication. The motivation cited to modify Akram with the interrogation system of Larson was “saving power on the isolated substrate having limited supply of power by transmitting only intermittently.” However, the substrate of Akram does not appear to be isolated because it is connected via connections 14. Akram discloses “An electrical signal entering via one of electrical interconnects 40, 41 passes through temperature sensing device 30a and exits through the opposite electrical interconnect,” column 7, lines 11-14. Akram also discloses, “Interface connection 18 is configured to provide electrical coupling of electrical interconnects 40, 41 and the respective temperature sensing devices 30 with circuitry 12 external of electronic device workpiece 10,” column 4, line 64 - column 5, line1. Thus, workpiece 10 of Akram appears to receive power from circuitry 12, which includes connections 10. Replacing such a hard wired system with a wireless system and an isolated substrate would appear to create a problem of “the isolated substrate having a limited supply of power.” Therefore, modifying Akram to use a wireless interrogation system such as that of Larson would appear to be contrary to the cited motivation. In addition, the substrate of claim 30 is not isolated as there are “leads connecting the substrate to the electronics module.” Therefore, it is not seen how the cited motivation could lead to the claimed structure.

Claim 31 was rejected over a combination of Akram, Larson and Lauf. The Office cites Lauf as “connecting RF wireless communication interface with the conditioning circuit to eliminate wiring.” However, it is not seen how this provides a motivation to achieve a structure including “leads connecting the substrate to the electronics module.” In particular, if elimination of wiring is cited as a motivation it is not clear how this suggests the desirability of the structure of claim 31 that requires leads.

Claim 32 recites “the transceiver transmits and receives sonic signals.” Output pad 26 of Smesney was cited as teaching this claim element. The motivation cited to combine Smesney with Akram was “to provide alternatively mechanical, optical or acoustic (sonic) connection to external output device. Having alternative apparatus useful for performing the same function provides for advantageous design choices.” It is unclear what is meant by “advantageous design choices” and because any advantages that might be provided have not been identified in the Office Action, it is submitted that a *prima facie* case of obviousness has not been made with respect to claim 32. Therefore, it is requested that the rejection be withdrawn.

Claim 36 is amended to clarify antecedent basis for a claim element.

Claim 45 is amended to clarify the antecedent basis referenced in claim 21. Claim 45 recites “in a first position the electronics module is above or below the substrate, and in a second position the electronics module and the substrate are displaced from each other such that the first and second perimeter do not intersect.” Claim 45 was rejected as anticipated by Figure 1 of Akram. However, Figure 1 of Akram appears to show the electronics module in a single position with respect to the substrate. It is not clear whether this is cited as the first position or second position but in either case it appears that the two positions of claim 45 have not been shown. Therefore, claim 45 is submitted to be additionally allowable.

New claims

Claims 46-54 are added by this amendment. Claims 46-54 are believed to be supported throughout the application and in particular by Figures 1A-F, 2 and 3A. Claims 46-54 are directed to subject matter that is related to the subject matter of pending claims

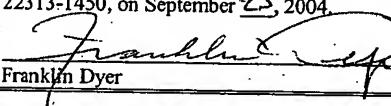
21-36 and 45. Claims 46-54 are submitted to be allowable for similar reasons to those given with respect to claims 21-36 and 45.

Conclusion

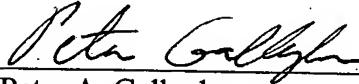
Accordingly, it is believed that all claims are now in condition for allowance and an indication of their allowance is requested. However, if the Examiner is aware of any matters that should be discussed, a phone call to the undersigned attorney at (415) 318-1160 would be appreciated.

Certificate of Mailing Under 37 CFR 1.8

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on September 23, 2004.


Franklin Dyer

Respectfully submitted,



Peter A. Gallagher
Reg. No.47,584

9/23/04
Date

MAIL STOP AMENDMENT
COMMISSIONER FOR PATENTS
P.O. BOX 1450
ALEXANDRIA, VA 22313-1450

Applicants: Wayne Renken
Title: Process Condition Sensing Wafer and Data Analysis System
Application No.: 10/685,550
Filing Date: October 14, 2003
Conf. No.: 4924
Atty Docket No.: SENS.005US1

ENCLOSED:

1. This Return Receipt Postcard
2. Transmittal Letter (1 page)
3. Amendment (12 pages)

PAG/fwd Due Date: September 29, 2004 Mailing Date: September 23, 2004

MAIL STOP AMENDMENT
COMMISSIONER FOR PATENTS
P.O. BOX 1450
ALEXANDRIA, VA 22313-1450

Applicants: Wayne Renken
Title: Process Condition Sensing Wafer and Data Analysis System
Application No.: 10/685,550
Filing Date: October 14, 2003
Conf. No.: 4924
Atty Docket No.: SENS.005US1

ENCLOSED:

1. This Return Receipt Postcard
2. Transmittal Letter (1 page)
3. Amendment (12 pages)

PAG/fwd Due Date: September 29, 2004 Mailing Date: September 23, 2004



RECEIVED
OCT 05 2004
Parsons Hsue & de Runtz LLP JMW

655 Montgomery Street, Suite 1800 San Francisco, Ca 94111
 tel 415.318.1160 fax 415.693.0194



Date February 16, 2005
To United States Patent and Trademark Office
Examiner Charles D. Garber
Fax number (703) 872-9306
Tel number (571) 272-2194

From Peter A. Gallagher, Reg. No. 47,584
Total pages 17
Subject Response to Notice of Abandonment dated February 7, 2005
Your Ref. Application No. 10/685,550
Our Ref. SENS.0005US1

COMMISSIONER FOR PATENTS
P.O. BOX 1450
ALEXANDRIA, VA 22313-1450

Applicants: Wayne G. Renken
 Title: Process Condition Sensing Wafer and Data Analysis Systems
 Patent No.:
 Issue Date:
 Application No.: 10/685,550
 Filing Date: October 14, 2003
 Conf. No.: 4924
 Atty Docket No.: SENS.0005US1

ENCLOSED:

1. This Fax Cover Sheet (1 page)
2. Response to Notice of Abandonment (2 pages)
3. Copy of Amendment Transmittal dated September 23, 2004 (1 page)
4. Copy of Amendment in response to June 29, 2004 Office Action dated September 23, 2004 (12 pages)
5. Copy of Return Receipt Postcard with a mailing date of September 23, 2004, date-stamped by the Patent and Trademark Office September 27, 2004 (1 page)

PAG/haj.

Confirmation Report - Memory Send

OPIE
JUL 28 2005
SEARCHED
SERIALIZED
FILED
Page : 001
Date & Time: 16-Feb-2005 11:37am
Line 1 : 4156930196
Machine ID : PARSONS HSUE & DE RUNTZ LLP

Job number : 534
Date : 16-Feb 11:32am
To : 17038729306
Number of pages : 017
Start time : 16-Feb 11:32am
End time : 16-Feb 11:37am
Pages sent : 017
Status : OK
Job number : 534

*** SEND SUCCESSFUL ***

PARSONS HSUE & DE RUNTZ LLP

655 Montgomery Street, Suite 1800 San Francisco, Ca 94111
tel 415.318.1160 fax 415.693.0194

Date	February 16, 2005
To	United States Patent and Trademark Office
Fax number	Examiner Charles D. Garber
Tel number	(703) 872-9306 (571) 272-2194
From	Peter A. Gallagher, Reg. No. 47,584
Total pages	17
Subject	Response to Notice of Abandonment dated February 7, 2005
Your Ref.	Application No. 10/685,550
Our Ref.	SENS.0005US1

COMMISSIONER FOR PATENTS
P.O. BOX 1450
ALEXANDRIA, VA 22313-1450

Applicants: Wayne G. Renken
Title: Process Condition Sensing Wafer and Data Analysis Systems
Patent No.:
Issue Date:
Application No.: 10/685,550
Filing Date: October 14, 2003
Conf. No.: 4924
Atty Docket No.: SENS.0005US1

ENCLOSED:

1. This Fax Cover Sheet (1 page)
2. Response to Notice of Abandonment (2 pages)
3. Copy of Amendment Transmittal dated September 23, 2004 (1 page)
4. Copy of Amendment in response to June 29, 2004 Office Action dated September 23, 2004 (12 pages)
5. Copy of Return Receipt Postcard with a mailing date of September 23, 2004, date-stamped by the Patent and Trademark Office September 27, 2004 (1 page)

PAG/baj



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s):

Wayne G. Renken

Assignee:

SensArray Corporation

Title:

Process Condition Sensing Wafer and Data Analysis System

Application No.:

10/685,550

Filing Date:

October 14, 2003

Examiner:

Charles D. Garber

Group Art Unit: 2856

Docket No.:

SENS.005US1

Conf. No.:

4924

Certificate of Transmission Under 37 CFR 1.8

I hereby certify that this correspondence is being facsimile transmitted to the United States Patent and Trademark Office on February 16, 2005

Helen A. Jackson
Helen A. Jackson

San Francisco, California
February 16, 2005

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO NOTICE OF ABANDONMENT

Sir:

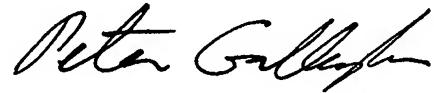
Applicant hereby responds to the Notice of Abandonment dated February 7, 2005, in the above-referenced application wherein the Examiner states that a response was never received to the Office Action dated June 29, 2004.

Applicant submits that this notice was sent in error. A timely response was mailed on September 23, 2004. Attached are copies of

1. Return Receipt Postcard date stamped September 27, 2004;
2. Amendment Transmittal; and
3. Amendment in response to June 29, 2004, Office Action (12 pages).

In view of the above, we respectfully request that the holding of abandonment be withdrawn. If a telephone call would expedite this request, please call Attorney for Applicant shown below at (415) 318-1160.

Respectfully submitted,



Peter A. Gallagher
Attorney for Applicant
Reg. No. 47,584

PARSONS HSUE & DE RUNTZ LLP.
655 Montgomery Street, Suite 1800
San Francisco, CA 94111
(415) 318-1160 (main)
(415) 318-1163 (direct)
(415) 693-0194 (fax)

**This Page is Inserted by IFW Indexing and Scanning
Operations and is not part of the Official Record**

BEST AVAILABLE IMAGES

Defective images within this document are accurate representations of the original documents submitted by the applicant.

Defects in the images include but are not limited to the items checked:

- BLACK BORDERS**
- IMAGE CUT OFF AT TOP, BOTTOM OR SIDES**
- FADED TEXT OR DRAWING**
- BLURRED OR ILLEGIBLE TEXT OR DRAWING**
- SKEWED/SLANTED IMAGES**
- COLOR OR BLACK AND WHITE PHOTOGRAPHS**
- GRAY SCALE DOCUMENTS**
- LINES OR MARKS ON ORIGINAL DOCUMENT**
- REFERENCE(S) OR EXHIBIT(S) SUBMITTED ARE POOR QUALITY**
- OTHER:** _____

IMAGES ARE BEST AVAILABLE COPY.

As rescanning these documents will not correct the image problems checked, please do not report these problems to the IFW Image Problem Mailbox.